

Title (en)
ELECTROMAGNETIC SHIELDING MATERIAL

Title (de)
MATERIALIEN ZUR ELEKTROMAGNETISCHEN ABSCHIRMUNG

Title (fr)
MATÉRIAU DE PROTECTION ÉLECTROMAGNÉTIQUE

Publication
EP 2154950 A1 20100224 (EN)

Application
EP 08755449 A 20080514

Priority
• US 2008063595 W 20080514
• US 80377307 A 20070516

Abstract (en)
[origin: WO2008144336A1] An electromagnetic shielding material includes a paper web and a conductive layer adhered to an adjacently positioned surface of the paper web. This arrangement defines a laminate structure that, when interposed between a receiving antenna of an RFID smart chip and a transmitting antenna of a signal generator, prevents the reading of the chip. A security device capable of electromagnetically shielding an RFID smart chip includes an electromagnetic shielding material having at least one conductive layer and at least one adjacently positioned substrate. A method of electromagnetically shielding an RFID smart chip includes providing and placing an electromagnetic shielding material proximate an RFID smart chip and preferably between the RFID smart chip and a transmitting antenna of an RFID signal generator.

IPC 8 full level
A01K 1/015 (2006.01); **G06K 19/073** (2006.01); **H05K 9/00** (2006.01)

CPC (source: EP)
B32B 15/08 (2013.01); **B32B 15/12** (2013.01); **B32B 15/20** (2013.01); **B32B 27/06** (2013.01); **B32B 27/10** (2013.01); **B32B 27/18** (2013.01); **B32B 27/32** (2013.01); **B32B 27/36** (2013.01); **B32B 29/00** (2013.01); **G06K 19/07327** (2013.01)

Designated contracting state (EPC)
AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MT NL NO PL PT RO SE SI SK TR

Designated extension state (EPC)
AL BA MK RS

DOCDB simple family (publication)
WO 2008144336 A1 20081127; AU 2008255083 A1 20081127; CN 101730464 A 20100609; EP 2154950 A1 20100224; EP 2154950 A4 20100623; JP 2011508408 A 20110310; TW 200906609 A 20090216

DOCDB simple family (application)
US 2008063595 W 20080514; AU 2008255083 A 20080514; CN 200880023974 A 20080514; EP 08755449 A 20080514; JP 2010508557 A 20080514; TW 97117804 A 20080515